

# **Documentation Updates and Changes**

GT-64240 and GT-64260 Datasheets Rev. 1.1, Dated Dec. 18, 2000 Feb 22, 2001 Rev. 1.0 DCU-64120B-0010

## Introduction

This document provides changes to the GT-64240 and GT-64260 Datasheets Rev. 1.1, Dated Dec. 18, 2000.

These changes will appear in a future release of these datasheet.

# **Datasheet Corrections/Updates**

Change #1: Section 2. Pin Information (GT-64240 Only)

Table 3: CPU Interface Pin Assignments (page 25)

#### **Description**

The following information must be noted when working with these pins:

#### **Table 1: Additional CPU Pin Information**

Pin Name/ Ball #	Туре	Full Name	Description
PReq* A26	I	Processor Request	CPU requests from the GT–64240/60 for SysAD bus mastership.  NOTE: If interfacing with a CPU that does not support Preq*, pull up is required on this pin.
TcTCE* G30	I	Ternary Cache Tag RAM Chip Enable	The CPU L3 cache controller signals that it is accessing L3 cache.  NOTE: If interfacing with a CPU that does not support TcTCE*, pull up is required on this pin.
TcMatch C29	I	Ternary Cache Tag Match	Asserted by tag RAM on L3 cache tag match.  NOTE: If there is no L3 cache, connect the TcMatch input to GND.

Change #2: Table 97: CPU Configuration, Offset: 0x000 (GT-64260 Only) (page 90)

## **Description**

The AACK Delay bit [11] is not supported in the MPX mode. The GT-64260 always asserts AACK\* on the cycle after  $\mathtt{TS*}$ , as if AACK Delay is set to '0'.

Change #3: Section 4.21.2 CPU Control Registers (GT-64260 Only)

Table 99: CPU Master Control, Offset: 0x160 (page 93)

## Description

Clarification that when running in MPX mode the IntArb bit [8] must be set to '1'.



# Documentation Updates and Changes GT-64240 and GT-64260 Datasheets Rev. 1.1, Dated Dec. 18, 2000

Change #4: Section 5.15.1 SDRAM Configuration Registers (GT-64240)

Table 127: SDRAM Configuration, Offset 0x448(page 120)

Section 5.15.1 SDRAM Configuration Registers (GT-64260) Table 144: SDRAM Configuration, Offset 0x448 (page 130)

# **Description**

Bits [15:14] are reversed in the datasheet rev. 1.1. The correct functionality is as follows:

 Table 2:
 Enable Virtual and Enable Physical Banks Settings

Bits	Field Name	Function	Initial Value
14	VInterEn	Enable Virtual banks (within the same SDRAM device) Interleaving 0 - Interleaving enabled 1 - Interleaving disabled	0x0
15	PhInterEn	Enable Physical banks (SCS[3:0]*) Interleaving 0 - Interleaving enabled 1 - Interleaving disabled	0x0

Change #5: Section 7. Device Controller (GT-64240) (page 136)

Section 7. Device Controller (GT-64260) (page 146)

### **Description**

In future revisions, a new note will be added to this section that states:

All device controller signals, including <code>CSTiming\*</code>, are floated for the entire reset assertion period and an additional five <code>TClk</code> cycles after reset deassertion. Since the device chip select is qualified with <code>CSTiming\*</code>, this signal must be pulled up or driven for the five additional cycles by some external logic, to prevent undesired accesses to the device.

# Documentation Updates and Changes GT-64240 and GT-64260 Datasheets Rev. 1.1, Dated Dec. 18, 2000

Change #6: Section 14.6.4 Channel Registers (CHxRx) for HDLC Mode (GT-64240)

Table 597: CHR10 - Event Status Register (ESR) (page 407 Section 14.8.5 Channel Registers (CHxRx) for UART Mode)
Table 611: CHR10 - UART Event Status Register (ESR) (page 432

Section 15.6.4 Channel Registers (CHxRx) for HDLC Mode (GT-64260)

Table 637: CHR10 - Event Status Register (ESR) (page 428)

15.8.5 Channel Registers (CHxRx) for UART Mode

Table 651: CHR10 - UART Event Status Register (ESR) (page 453)

#### **Description**

For field RHS bit [5], the following settings apply:

#### Table 3: Rx in Hunt State Mode Settings

Mode	Setting '0'	Setting '1'	
HDLC	Rx out of hunt state.	Rx in hunt state	
UART	Rx in hunt state	Rx out of hunt state.	

#### Change #7: Section 15.1 SDMA Overview (GT-64240) (page 441)

Section 16.1 SDMA Overview (GT-64260) (page 462)

## **Description**

Incorrectly states that there are three SDMA channels.

The part contains only two SDMA channels.

## Change #8: Section 19.4 MPP Interface Registers (GT-64240) (page 468)

Section 20.4 MPP Interface Registers (GT-64260) (page 489)

## Description

In the MPP Control2 register table, the correct offset is **0xf008**. The published offset 0xf0008 is incorrect.

The correct offset for the MPPControl3 is 0xf00c.



# Documentation Updates and Changes GT-64240 and GT-64260 Datasheets Rev. 1.1, Dated Dec. 18, 2000

Change #9: Section 24.1 Pins Sample Configuration (GT-64240)

Table 683: Reset Configuration (page 505)

Section 25.1 Pins Sample Configuration (GT-64260)

**Table 723: Reset Configuration (page 526)** 

#### **Description**

The setting for AD[30] Bypass PLL are:

- 0: PLL Enabled (pull down)
- 1: PLL Disabled (pull up)

Also, for GT–64240 only, AD[7:6] must be strapped to 10.

#### Change #10: Section 24.2 Serial ROM Initialization (GT-64240) (page 508)

Section 25.2 Serial ROM Initialization (GT-64260) (page 529)

### **Description**

When using serial ROM, the pins AD[3:0] and AD[31:28] must be configured (pulled up or pulled down) as specified in the reset configuration table. These pins that control the serial ROM initialization, PLL configuration, and the CPU interface voltage.

#### Change #11: Section 26.4 Thermal Data (GT-64240)

Table 688: Thermal Data for The GT-64240 in BGA 665 (page 516)

Section 27.4 Thermal Data (GT-64260)

Table 728: Thermal Data for The GT-64260 in BGA 665 (page 537)

#### **Description**

Disregard all the information about thermal management contained in this section before the thermal data table. For further information, see AN-63: Thermal Management for Galileo Technology Products.

Corrected the junction to ambient thermal resistance symbol. The following table uses the correct symbols.



#### Note

The values are unchanged from the datasheet. The only change was to the junction to ambient thermal resistance symbol.



## Table 4: Thermal Data for The GT-64240/60 in BGA 665

		Value		
Airflow	Definition	0 m/s	1 m/s	2 m/s
Θја	Thermal resistance: junction to ambient.	13.3 C/W	12.1 C/W	10.8 C/W
Ψjt	Thermal characterization parameter: junction to case center.	0.28 C/W	0.31 C/W	0.38 C/W
Θјс	Thermal resistance: junction to case (not air-flow dependent)		4.7 C/W	

Change #12: Section 27 AC Timing (GT-64240)

Table 689: AC Timing (page 520)

Section 28 AC Timing (GT-64260) Table 729: AC Timing (page 537)

## **Description**

In the Device Interface section of the AC Timing table, the 3ns setup parameter for Ready\* only applies if the Device Interface Control register's ReadyS\* field (bit[18]) is set to '1'.